

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L072CBT6	S95B*447XXXZ	A	998Z	28-09-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	190.98	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7X7X1.4	48	L Bend	
Comment	Package : 58 LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	S95B*447XXXZ				6000001.0	-1.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.860	mg	supplier	die	Silicon (Si)	7440-21-3		4.555	mg	937243	23850
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	5556	141
				supplier	metallization	Copper (Cu)	7440-50-8		0.088	mg	18107	461
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.010	mg	2058	52
				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	2675	68
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	206	5
				supplier	Passivation	Silicon Nitride	12033-89-5		0.024	mg	4938	126
				supplier	Passivation	Silicon Oxide	7631-86-9		0.142	mg	29218	744
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	1.278	mg	Supplier	Metals	Silver	7440-22-4		1.151	mg	901000	6028
				Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0.126	mg	99000	662
Mold Compound_EME-G631SHQ_Sur	M-011 Other inorganic materials	120.458	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.434	mg	21000	13406
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.434	mg	21000	13406
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		6.492	mg	56000	35750
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		95.006	mg	780450	-526870
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		13.369	mg	115320	73619
Wire_Ag Si Type_MKE	Bonding Wire	0.309	mg	Supplier	Non-metals	Carbon Black	1333-86-4		0.722	mg	6230	3977
				Supplier	Metals	Silver	7440-22-4		0.297	mg	960000	1634
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1.078	mg	Supplier	Others	Others	Proprietary		0.012	mg	40000	68
				Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	5939
Leadframe_C194+Ag_HDS	Copper & its alloys	63.000	mg	Supplier	Metals	Iron	7439-89-6		1.377	mg	21865	7586
				Supplier	Non-metals	Phosphorus	7723-14-0		0.046	mg	730	253
				Supplier	Metals	Zinc	7440-66-6		0.071	mg	1125	390
				Supplier	Metals	Copper	7440-50-8		57.534	mg	913235	316831
				Supplier	Metals	Silver	7440-22-4		3.969	mg	63000	21857
				JIG-R	Metals	Lead	7439-92-1		0.003	mg	45	16